

Jonathan Platt

www.linkedin.com/in/JonathanTPlatt

Education

Bachelor of Science in Computer Engineering, May 2021

Major: Computer Engineering, Math

GPA: 4.0/4.0

Master of Science in Electrical Engineering, May 2022

GPA: 4.0/4.0

The University of Alabama, Tuscaloosa, AL

Minors: Randall Research Scholars, Computer Science

The University of Alabama, Tuscaloosa, AL

Publication & Presentations

Hoyun Won, Katelyn Isbell, Leo Vanderburgh, Jonathan Platt, Woncheol Lee, and Yang-Ki Hong, "Developing a Direction-Finding System and Channel Sounder using a Pseudo-Doppler Antenna Array," in *IEEE Antennas and Propagation Magazine*, Volume 61, Number 4, pp. 84-89, August 2019.

Hoyun Won, Yang-Ki Hong, Katelyn Isbell, Leo Vanderburgh, and Jonathan Platt, "Evaluation on Pseudo-Doppler Antenna Array using Software-Defined-Radio," in *2019 IEEE International Symposium on Antennas and Propagation and USNC-URSI Radio Science Meeting*, Atlanta, GA, USA, 2019, pp. 1835-1836.

Work Experience

Magnetic Materials and Device Lab

Undergraduate Research Assistant

The University of Alabama, Tuscaloosa, AL

November 2017 – Present

- Participated in 2018 Antenna Propagation Society (APS) student design contest with 4 other students by programming the digital signal processing for a novel radiolocation system using open source software
- Presented as a finalist at the 2018 IEEE APS Symposium in Boston, Massachusetts on a poster with a technical report and was awarded 2nd place among 6 international finalist teams
- Researched, developed, and analyzed an original low loss and lightweight composite antenna substrate using metal ferrites and commercially available plastic resin
- Presented progress to students and faculty at on campus undergraduate research conferences

United States Air Force Civilian Service

Electronics Reverse Engineering Intern

Warner Robins, GA

May – July 2020

- Reverse engineered circuit board design of 1970s era aircraft with limited documentation on accelerated 3-month timeline
- Created and submitted a technical data package to client consisting of a bill of materials, circuit schematic, board layout files, assembly drawing, testing procedure, list of faults, and repair plan 1 week ahead of schedule
- Performed failure analysis on two 50+ component boards by identifying faulty components on par with trained technician

Church & Dwight

Product Engineering Intern

Princeton, NJ

May – August 2019

- Developed operating procedure for new 3D printer resulting in a 50% increase in prototyping capacity
- Diagnosed and documented embedded system software for use in new consumer product line, accelerating project timeline from 5 to 4 months
- Designed, created, and used test fixtures to evaluate manufactured product consistency and quality in-house saving hundreds of dollars over a three-week period compared to contracted work

Skills & Certifications

Computer Aided Design Software: Altium, Autodesk Inventor, Cura, OrCAD PSpice, Repetier, Simplify3D, SolidWorks

Software Engineering: C, C++, C#, Fortran, Git, Java, Javascript, Linux, MATLAB, MIPS Assembly, Python, SQL, VHDL, Verilog

RF Engineering: Anechoic Chamber, ANSYS HFSS, Impedance Analyzer, Software Defined Radio, VNA, VSM

Other: 3D Printing, Machining, Project Management, Problem Solving, ScanCAD, Inactive Security Clearance

Leadership & Extracurriculars

Eta Kappa Nu (Electrical Engineering Honors Society), Member, 04/2019 - Present

Institute of Electronical and Electronics Engineers (IEEE), President, 04/2018 - Present

Alabama Astrobotics, Electrical Team Member, 11/2017 - Present

Million Dollar Band, Member, 08/2017 - Present

Honors

Henry Copeland Scholarship, Randall Research Scholars, 06/2020

CES Outstanding Senior - Computer Engineering, Electrical and Computer Engineering Department, 04/2019

Outstanding Undergraduate Research Award, Electrical and Computer Engineering Department, 04/2019

Fred R. Maxwell Jr. Award, Electrical and Computer Engineering Department, 03/2019

Eagle Scout, Boy Scouts of America, 07/2017